



General Description

The HSCA2030 is the highest performance trench N-ch MOSFETs with extreme high cell density , which provide excellent RDSON and gate charge for most of the small power switching and load switch applications.

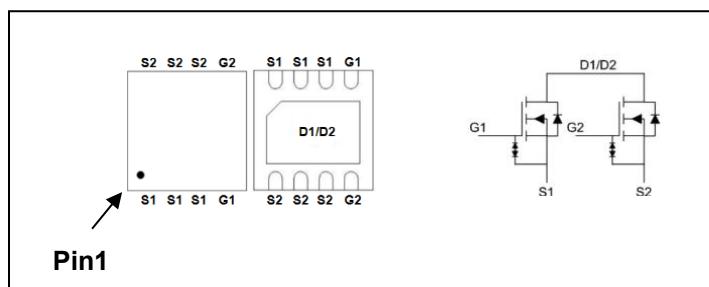
The HSCA2030 meet the RoHS and Green Product requirement with full function reliability approved.

Product Summary

V _{DS}	20	V
R _{DS(ON),max}	5.8	mΩ
I _D	56	A

DFN3x3 Pin Configuration

- Green Device Available
- Super Low Gate Charge
- Excellent CdV/dt effect decline
- Advanced high cell density Trench technology



Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V _{DS}	Drain-Source Voltage	20	V
V _{GS}	Gate-Source Voltage	±8	V
I _D @T _c =25°C	Continuous Drain Current, V _{GS} @ 4.5V ₁	56	A
I _D @T _c =100°C	Continuous Drain Current, V _{GS} @ 4.5V ₁	35.6	A
I _D @T _A =25°C	Continuous Drain Current, V _{GS} @ 4.5V ₁	19	A
I _D @T _A =70°C	Continuous Drain Current, V _{GS} @ 4.5V ₁	15	A
I _{DM}	Pulsed Drain Current ₂	100	A
P _D @T _c =25°C	Total Power Dissipation ₁	31	W
P _D @T _A =25°C	Total Power Dissipation ₁	3.6	W
T _{STG}	Storage Temperature Range	-55 to 150	°C
T _J	Operating Junction Temperature Range	-55 to 150	°C

Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
R _{θJA}	Thermal Resistance Junction-Ambient ₁	---	35	°C/W
R _{θJC}	Thermal Resistance Junction-Case ₁	---	4	°C/W



N-Channel Electrical Characteristics ($T_J=25^{\circ}\text{C}$, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	$\text{V}_{\text{GS}}=0\text{V}, \text{I}_D=250\mu\text{A}$	20	---	---	V
$\text{R}_{\text{DS(ON)}}$	Static Drain-Source On-Resistance ₂	$\text{V}_{\text{GS}}=4.5\text{V}, \text{I}_D=3\text{A}$	---	4.3	5.8	$\text{m}\Omega$
		$\text{V}_{\text{GS}}=3.9\text{V}, \text{I}_D=3\text{A}$	---	4.5	6.5	
		$\text{V}_{\text{GS}}=2.5\text{V}, \text{I}_D=3\text{A}$	---	5	7	
		$\text{V}_{\text{GS}}=1.8\text{V}, \text{I}_D=3\text{A}$	---	7	11	
$\text{V}_{\text{GS(th)}}$	Gate Threshold Voltage	$\text{V}_{\text{GS}}=\text{V}_{\text{DS}}, \text{I}_D=250\mu\text{A}$	0.4	---	1.0	V
I_{DSS}	Drain-Source Leakage Current	$\text{V}_{\text{DS}}=16\text{V}, \text{V}_{\text{GS}}=0\text{V}, \text{T}_J=25^{\circ}\text{C}$	---	---	1	uA
		$\text{V}_{\text{DS}}=16\text{V}, \text{V}_{\text{GS}}=0\text{V}, \text{T}_J=55^{\circ}\text{C}$	---	---	5	
I_{GSS}	Gate-Source Leakage Current	$\text{V}_{\text{GS}}=\pm 8\text{V}, \text{V}_{\text{DS}}=0\text{V}$	---	---	± 10	uA
g_{fs}	Forward Transconductance	$\text{V}_{\text{DS}}=5\text{V}, \text{I}_D=3\text{A}$	---	42	---	S
Q_{g}	Total Gate Charge (4.5V)	$\text{V}_{\text{DS}}=10\text{V}, \text{I}_D=3\text{A}$	---	38	---	nC
	Total Gate Charge (3.9V)		---	33	---	
Q_{gs}	Gate-Source Charge		---	4.5	---	
Q_{gd}	Gate-Drain Charge		---	12	---	
$\text{T}_{\text{d(on)}}$	Turn-On Delay Time	$\text{V}_{\text{DD}}=16\text{V}, \text{V}_{\text{GS}}=4.5\text{V}, \text{R}_G=6\Omega$	---	22	---	ns
T_r	Rise Time		---	41	---	
$\text{T}_{\text{d(off)}}$	Turn-Off Delay Time		---	77	---	
T_f	Fall Time		---	21	---	
C_{iss}	Input Capacitance	$\text{V}_{\text{DS}}=10\text{V}, \text{V}_{\text{GS}}=0\text{V}, \text{f}=1\text{MHz}$	---	3165	---	pF
C_{oss}	Output Capacitance		---	380	---	
C_{rss}	Reverse Transfer Capacitance		---	325	---	

Diode Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I_s	Continuous Source Current ₁	$\text{V}_{\text{G}}=\text{V}_{\text{D}}=0\text{V}$, Force Current	---	---	30	A
I_{SM}	Pulsed Source Current ₂		---	---	100	A
V_{SD}	Diode Forward Voltage ₂	$\text{V}_{\text{GS}}=0\text{V}, \text{I}_s=3\text{A}, \text{T}_J=25^{\circ}\text{C}$	---	---	1.2	V

Note :

- 1.The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper, $t \leq 10\text{s}$.
- 2.The data tested by pulsed , pulse width $\leq 10\text{us}$, duty cycle $\leq 1\%$



Typical Characteristics

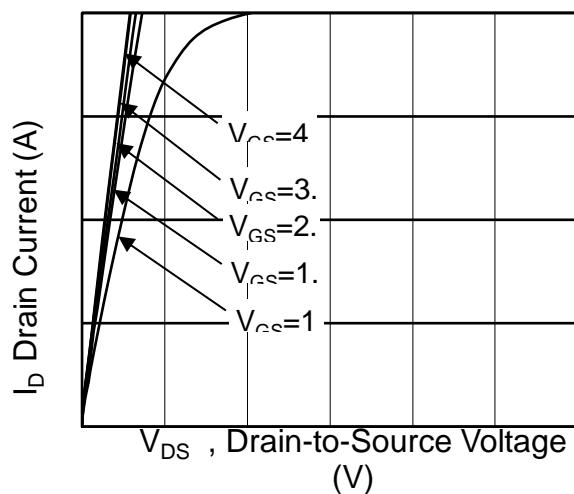


Fig.1 Typical Output Characteristics

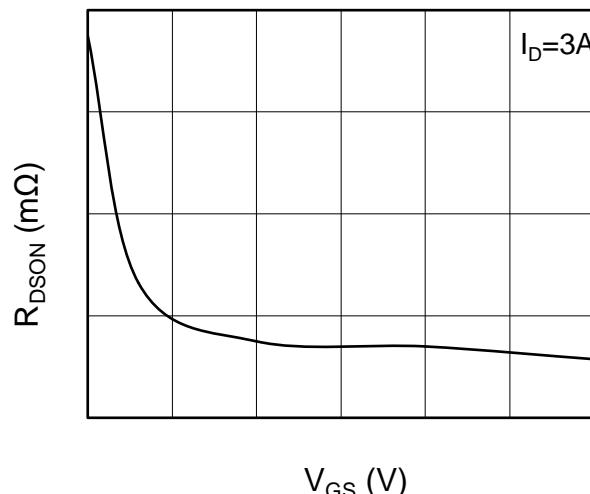


Fig.2 On-Resistance vs. Gate-Source

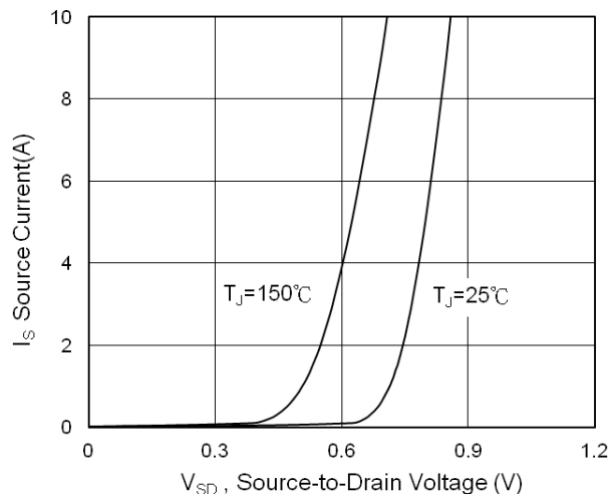


Fig.3 Forward Characteristics Of Reverse

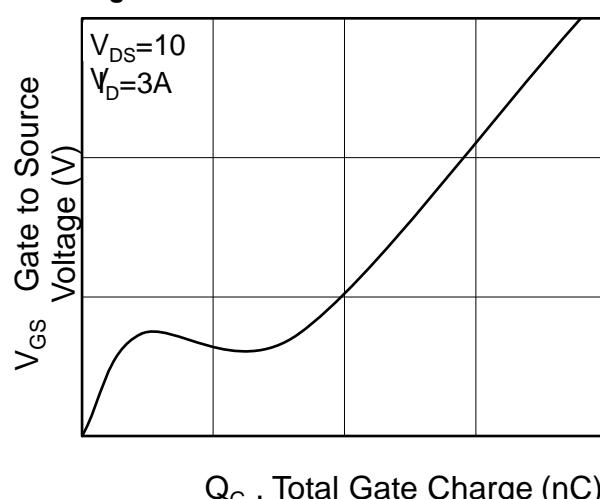


Fig.4 Gate-Charge Characteristics

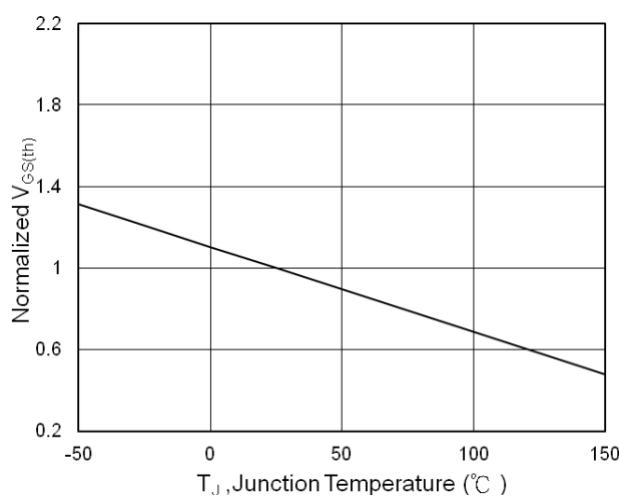


Fig.5 $V_{GS(th)}$ vs. T_J

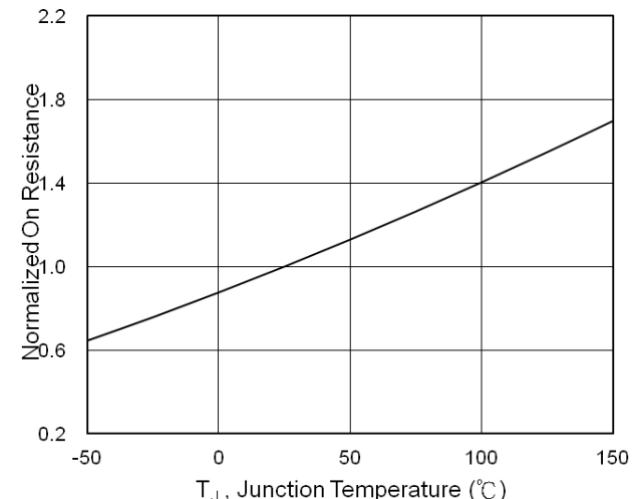


Fig.6 Normalized R_{DSON} vs. T_J



Dual N-Ch Fast Switching MOSFETs

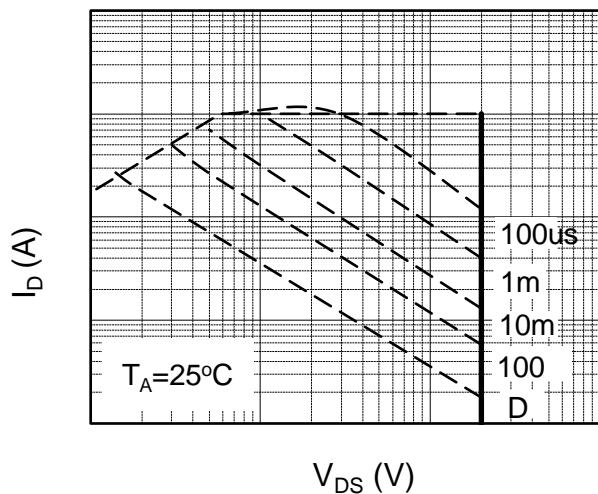
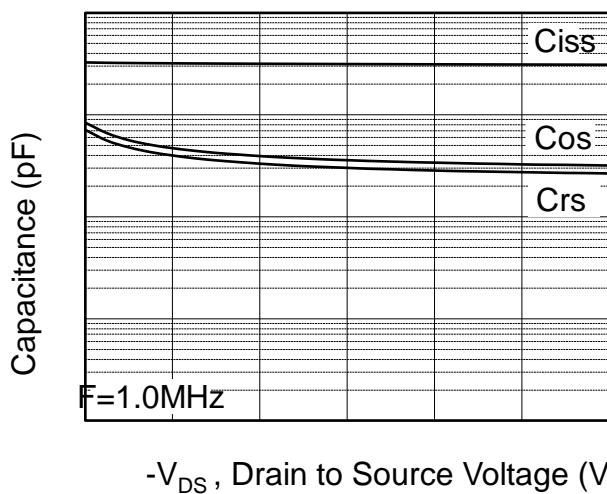


Fig.7 Capacitance



-V_{DS}, Drain to Source Voltage (V)

Fig.8 Safe Operating Area

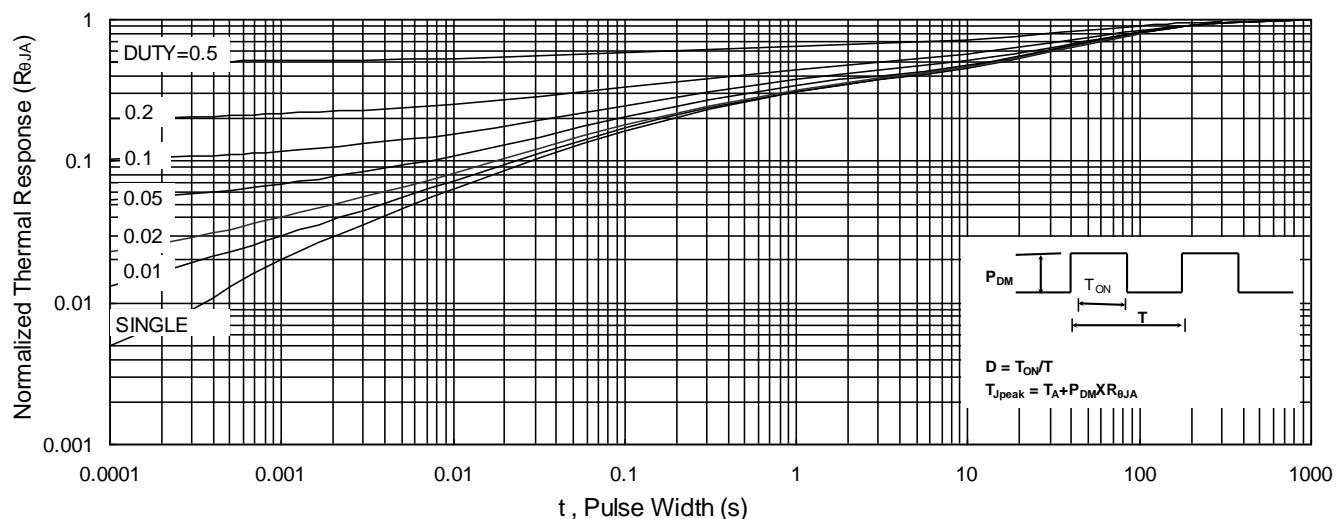


Fig.9 Normalized Maximum Transient Thermal Impedance

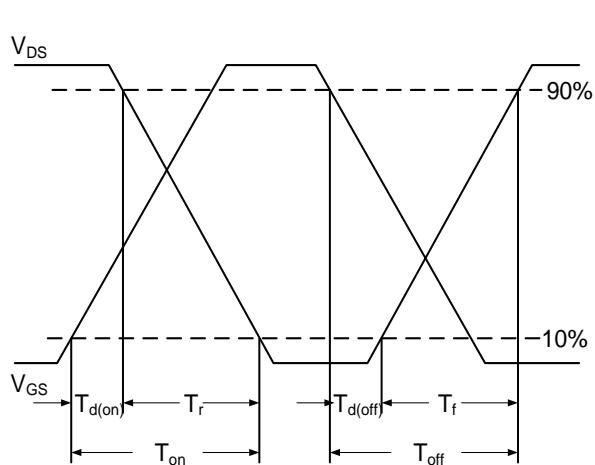


Fig.10 Switching Time Waveform

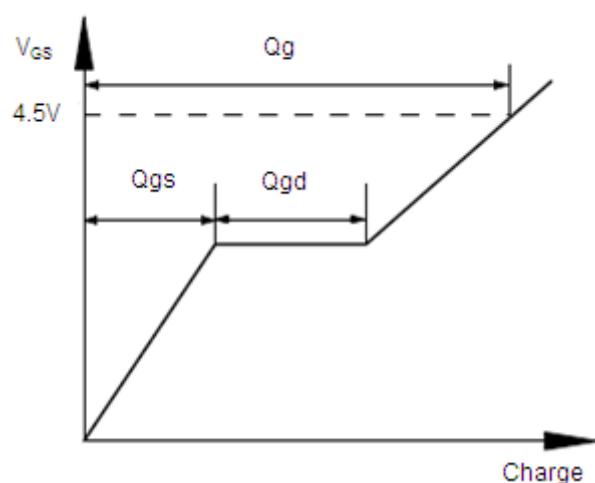
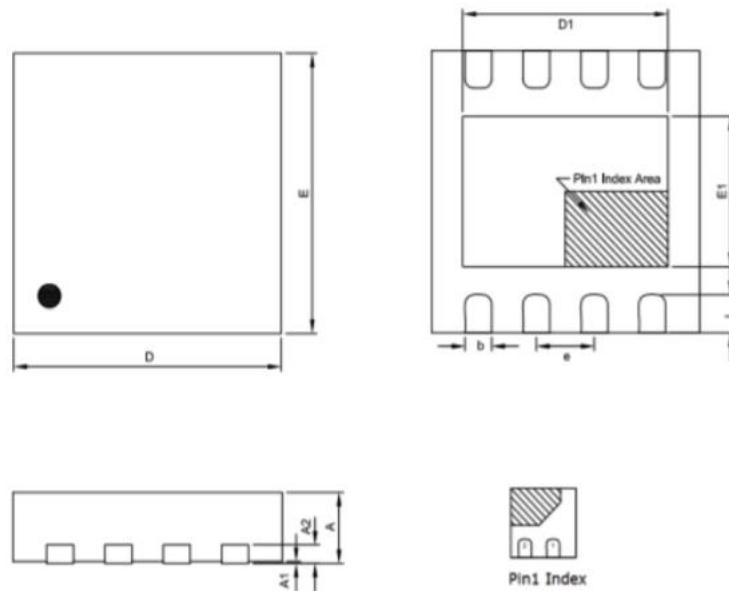


Fig.11 Gate Charge Waveform



DFN3x3 Package Outline Dimensions



SYMBOLS	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.70	0.75	0.80	0.0276	0.0295	0.0315
A1	0.00	--	0.05	0.000	--	0.002
A2	0.19	0.20	0.21	0.0075	0.0079	0.0083
D	2.90	3.00	3.10	0.114	0.118	0.122
E	2.90	3.00	3.10	0.114	0.118	0.122
D1	2.25	2.30	2.35	0.0886	0.0906	0.0925
E1	1.55	1.6	1.65	0.061	0.063	0.065
L	0.35	0.40	0.45	0.0138	0.0177	0.0207
b	0.25	0.30	0.35	0.0098	0.0118	0.0138
e	--	0.65	--	--	0.0256	--